REMARKS

The present invention is directed to a pressure sensitive adhesive. The pressure sensitive adhesive composition of the present invention can be applied without solvent or with almost no solvent; and the composition provides good pressure sensitive adhesive characteristics.[2] As shown in Table 1 of the present Specification, the pressure sensitive adhesive compositions of Examples 1 to 3 have low viscosity and provide pressure sensitive adhesive films with excellent adhesive strength.

This Amendment is filed in response to the non-final Office Action dated December 12, 2007, and is respectfully submitted to be fully responsive to the rejection raised therein. Accordingly, favorable reconsideration on the merits and allowance is respectfully submitted to be proper.

In the present Amendment, claim 1 has been amended to recite "pressure sensitive adhesive product obtained by curing a" in the preamble.

Claims 2 - 7 have been amended by deleting composition and inserting product.

No new matter has been added. Support for the Amendment can be found, e.g., on page 13, lines 28 to 30 in the specification.

Entry of the Amendment is respectfully submitted to be proper. Upon entry of the Amendment, claims 1-7 will be all the claims pending in the application.

Response to Claim Rejection Under 35 U.S.C. § 102(b)

Claims 1-7 were rejected under 35 U.S.C. § 102(b) as being anticipated by JP 2005-059267 ("Watabe").

---

[2] Specification, page 2, lines 13 to 16, for example.

The pressure sensitive adhesive product of the present claimed invention is obtained by curing the pressure sensitive adhesive composition comprising the components:

(A) A hydrolyzable silyl group-containing organic polymer containing at least 1.3 hydrolyzable silyl groups per molecule and having a number average molecular weight of 15,000 to 100,000;

(B) A hydrolyzable silyl group-containing organic polymer containing 0.3 to 1.3 hydrolyzable silyl groups per molecule and having a number average molecular weight of 500 to 15,000, the main chain of which polymer being substantially composed of a repeating unit or units represented by the general formula $-R^1-O-$ (R^1 being a divalent alkylene group);

(C) A tackifier resin; as recited in claim 1.

Watabe discloses a curable composition comprising a polypropylene polymer (I) containing hydrolysable silicon groups and having a high molecular weight and a low molecular weight compound (II) containing hydrolysable silicon groups and having a main chain of polyether.

Watabe teaches that the composition has a lower viscosity. Further, the composition contains a lower migrating additive and does not cause staining around the sealed part when it is used as a sealing agent.

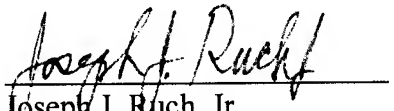
Although Watabe teaches flexibility, viscosity and migration of the composition, the document is silent about adhesive strength of the cured product. The composition of Watabe is used as a sealing material, and does not require a high adhesive strength.

Since Watabe is silent about an adhesive product having a high adhesive strength, the pressure sensitive adhesive product of the present invention is neither anticipated by nor rendered obvious by Watabe.

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned attorney at the local Washington, D.C. telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



Joseph J. Ruch, Jr.
Registration No. 26,577

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

WASHINGTON OFFICE
23373
CUSTOMER NUMBER

Date: March 12, 2008